

Title (en)  
CURABLE EPOXY RESIN COMPOSITION

Title (de)  
HÄRTBARE EPOXIDHARZZUSAMMENSETZUNG

Title (fr)  
COMPOSITION DE RÉSINE ÉPOXYDE DURCISSABLE

Publication  
**EP 2736941 A1 20140604 (EN)**

Application  
**EP 11738229 A 20110729**

Priority  
EP 2011063148 W 20110729

Abstract (en)  
[origin: WO2013017149A1] Curable epoxy resin composition comprising a defined aromatic epoxy resin component and a defined latent catalyst system, and optionally further additives, said curable composition being a single epoxy resin composition having a prolonged pot life at a processing temperature within the range of 40 °C to 70 °C, wherein: (a) the epoxy resin component is a compound of formula (I) in monomeric form or in a low polymeric form thereof, or is a mixture of such compounds: formula (I); D = -CH<sub>2</sub>-, -C(CH<sub>3</sub>)<sub>2</sub>-, -S-, -O-, -SO<sub>2</sub>-, -CO-; n = zero or one; said epoxy resin component having an inherent viscosity within the range of 80 mPas to 300 mPas, measured at a temperature of 50 °C; (b) the latent catalyst system comprises at least one metal acetylacetonate and at least one phenolic compound.

IPC 8 full level  
**C08L 63/00** (2006.01); **C08G 59/18** (2006.01); **C08G 59/24** (2006.01); **C08G 59/68** (2006.01); **H01B 3/40** (2006.01)

CPC (source: EP KR US)  
**C08G 59/18** (2013.01 - EP KR US); **C08G 59/245** (2013.01 - EP KR US); **C08G 59/68** (2013.01 - EP KR US); **C08L 63/00** (2013.01 - EP KR US); **H01B 3/40** (2013.01 - EP KR US)

Citation (search report)  
See references of WO 2013017149A1

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)  
**WO 2013017149 A1 20130207**; BR 112014001465 A2 20170221; BR 112014001465 B1 20201117; CN 103703048 A 20140402; CN 103703048 B 20160921; EP 2736941 A1 20140604; EP 2736941 B1 20160120; EP 2736941 B9 20160810; KR 101807194 B1 20171208; KR 20140056220 A 20140509; US 2014148529 A1 20140529; US 9418774 B2 20160816

DOCDB simple family (application)  
**EP 2011063148 W 20110729**; BR 112014001465 A 20110729; CN 201180072652 A 20110729; EP 11738229 A 20110729; KR 20147001616 A 20110729; US 201414167373 A 20140129